

Features

- Superior circuit protection
- Overcurrent and overvoltage protection
- Blocks surges up to rated limits
- High speed performance
- Small SMT package
- RoHS compliant*
- Agency recognition:

Applications

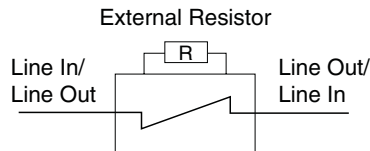
- Voice / VDSL cards
- Protection modules and dongles
- Process control equipment
- Test and measurement equipment
- General electronics

TBU-CX Series - TBU® High Speed Protectors

General Information

The TBU-CX Series of Bourns® TBU® products are low capacitance dual bidirectional high speed protection components, constructed using MOSFET semiconductor technology, and designed to protect against faults caused by short circuits, AC power cross, induction and lightning surges.

The TBU® high speed protector placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics will not be exposed to large voltages or currents during surge events. The TBU® device is provided in a surface mount DFN package and meets industry standard requirements such as RoHS and Pb Free solder reflow profiles.



Agency Approval

Description	
UL	File Number: E315805

Absolute Maximum Ratings (@ T_A = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Part Number	Value	Unit
V _{imp}	Peak impulse voltage withstand with duration less than 10 ms	TBU-CX025-VTC-WH	250	V
		TBU-CX040-VTC-WH	400	
		TBU-CX050-VTC-WH	500	
		TBU-CX065-VTC-WH	650	
		TBU-CX085-VTC-WH	850	
V _{rms}	Continuous A.C. RMS voltage	TBU-CX025-VTC-WH	100	V
		TBU-CX040-VTC-WH	200	
		TBU-CX050-VTC-WH	250	
		TBU-CX065-VTC-WH	300	
		TBU-CX085-VTC-WH	425	
T _{op}	Operating temperature range		-40 to +125	°C
T _{stg}	Storage temperature range		-65 to +150	°C
T _{jmax}	Maximum Junction Temperature		+125	°C
ESD	HBM ESD Protection per IEC 61000-4-2		±2	kV

Electrical Characteristics (@ T_A = 25 °C Unless Otherwise Noted)

Symbol	Parameter	Part Number	Min.	Typ.	Max.	Unit
I _{trigger}	Current required for the device to go from operating state to protected state (R _{external} = 0 ohm)	TBU-CXxxx-VTC-WH	500	750	1000	mA
R _{device}	Series resistance of the TBU device (R _{external} = 0 ohm)	V _{imp} = 250 V I _{trigger} (min.) = 500 mA	TBU-CX025-VTC-WH	2.6	3.0	Ω
		V _{imp} = 400 V I _{trigger} (min.) = 500 mA	TBU-CX040-VTC-WH	3.6	4.2	
		V _{imp} = 500 V I _{trigger} (min.) = 500 mA	TBU-CX050-VTC-WH	5.0	5.7	
		V _{imp} = 650 V I _{trigger} (min.) = 500 mA	TBU-CX065-VTC-WH	7.0	8.0	
		V _{imp} = 850 V I _{trigger} (min.) = 500 mA	TBU-CX085-VTC-WH	10.7	13.0	
t _{block}	Time for the device to go from normal operating state to protected state				1	μs
I _Q	Current through the triggered TBU® device with 50 Vdc circuit voltage		0.25	0.50	1.00	mA
V _{reset}	Voltage below which the triggered TBU® device will transition to normal operating state		12	16	20	V
R _{th(j-l)}	Junction to package pads - FR4 using recommended pad layout			98		°C/W
R _{th(j-l)}	Junction to package pads - FR4 using heat sink on board (6 cm ²) (1 in ²)			40		°C/W

*RoHS Directive 2002/95/EC Jan 27, 2003 including Annex.

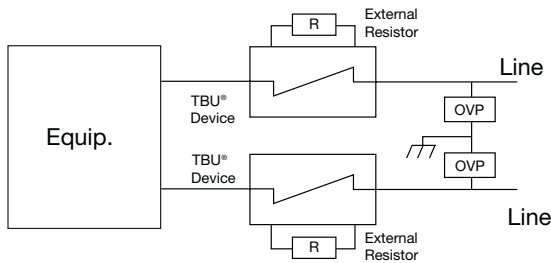
Specifications are subject to change without notice.

Customers should verify actual device performance in their specific applications.

Reference Application

The TBU® devices are general use protectors used in a wide variety of applications. The maximum voltage rating of the TBU device should never be exceeded. Where necessary, an OVP should be employed to limit the maximum voltage. A cost-effective protection solution combines Bourns® TBU® protection devices with a pair of Bourns® MOVs. For bandwidth sensitive applications, a Bourns® GDT may be substituted for the MOV. See “Trigger Current vs External Resistor Value” graph for selecting the optimum trigger current value using a 0 ohm – 50 ohm resistor value.

Note: Line Resistance =
 TBU® Device Resistance + R_{external} Resistance



Basic TBU Operation

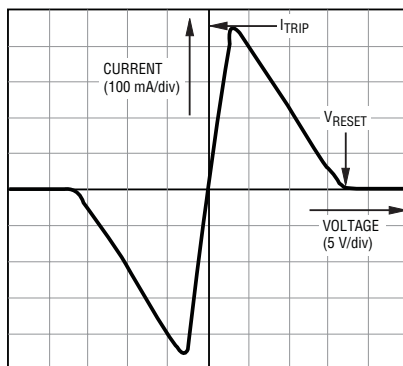
The TBU® device, constructed using MOSFET semiconductor technology, placed in the system circuit will monitor the current with the MOSFET detection circuit triggering to provide an effective barrier behind which sensitive electronics are not exposed to large voltages or currents during surge events. The TBU® device operates in approximately 1 μs - once line current exceeds the TBU® device's trigger current I_{trigger}. When operated, the TBU® device restricts line current to less than 1 mA typically. When operated, the TBU® device will block all voltages including the surge up to rated limits.

After the surge, the TBU® device resets when the voltage across the TBU® device falls to the V_{reset} level. The TBU® device will automatically reset on lines which have no DC bias or have DC bias below V_{reset} (such as unpowered signal lines).

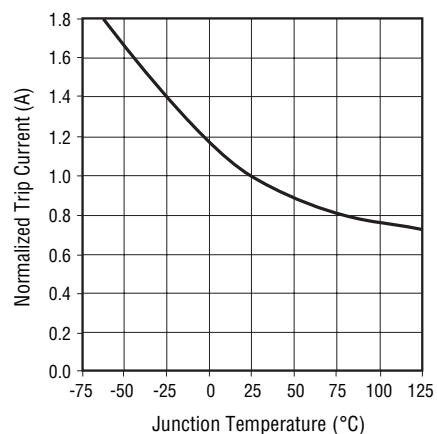
If the line has a normal DC bias above V_{reset}, the voltage across the TBU® device may not fall below V_{reset} after the surge. In such cases, special care needs to be taken to ensure that the TBU® device will reset, with software monitoring as one method used to accomplish this. Bourns application engineers can provide further assistance.

Performance Graphs

Typical V-I Characteristics (TBU-CX050-VTC-WH with R_{ext} = 1 Ω)



Typical Trigger Current vs. Temperature

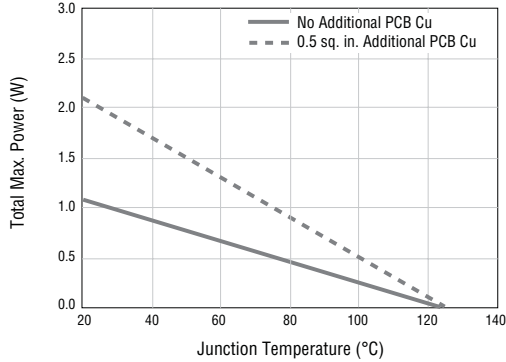


TBU-CX Series - TBU[®] High Speed Protectors

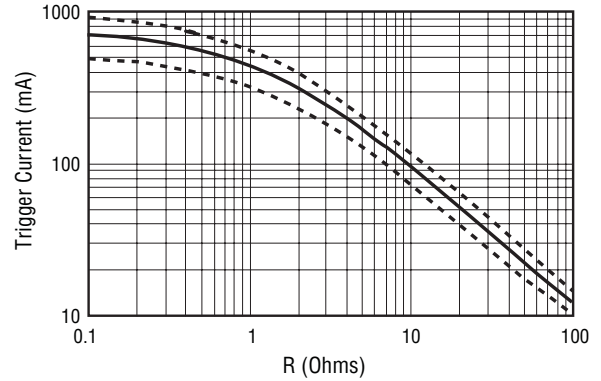
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Performance Graphs (Continued)

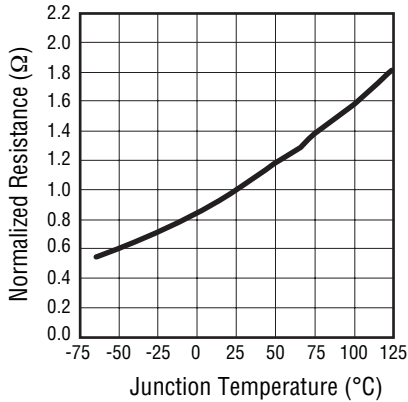
Power Derating Curve



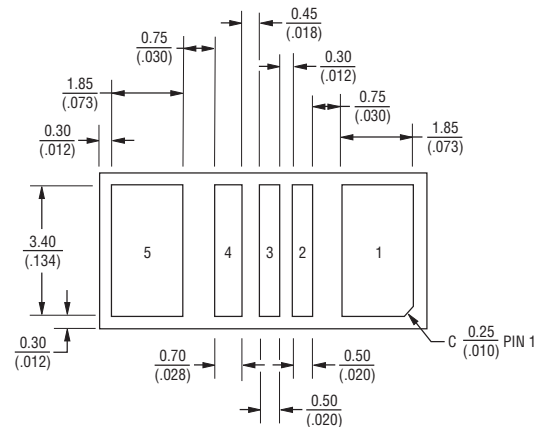
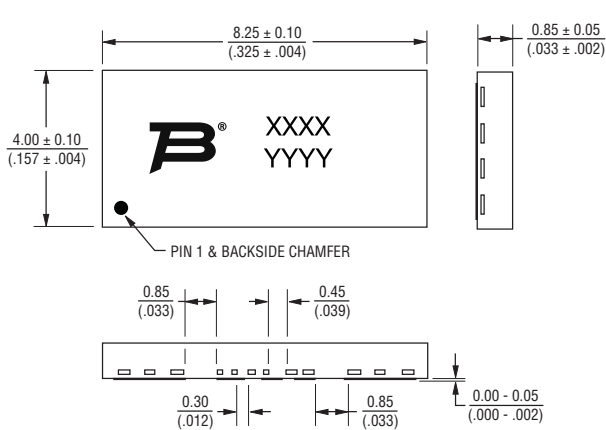
Trigger Current vs. External Resistor Value



Typical Resistance vs. Temperature



Product Dimensions



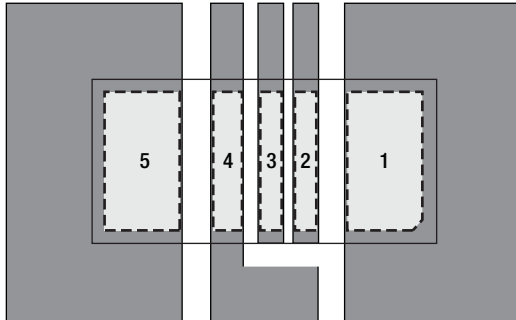
Pad Designation

Pad #	Pin Out
1	Line In/Out
2	External R Pad
3	External R Pad
4	NU
5	Line Out/In

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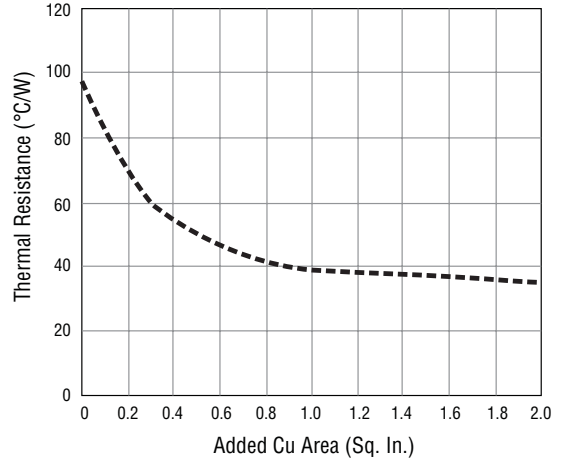
Recommended Pad Layout

TBU® protectors have matte-tin termination finish. The suggested layout should use Non-Solder Mask Define (NSMD). The recommended stencil thickness is 0.10-0.12 mm (.004-.005 in.) with a stencil opening size 0.025 mm (.0010 in.) less than the device pad size. As when heat sinking any power device, it is recommended that wherever possible, extra PCB copper area is allowed. For minimum parasitic capacitance, do not allow any signal, ground or power signals beneath any of the pads of the device.



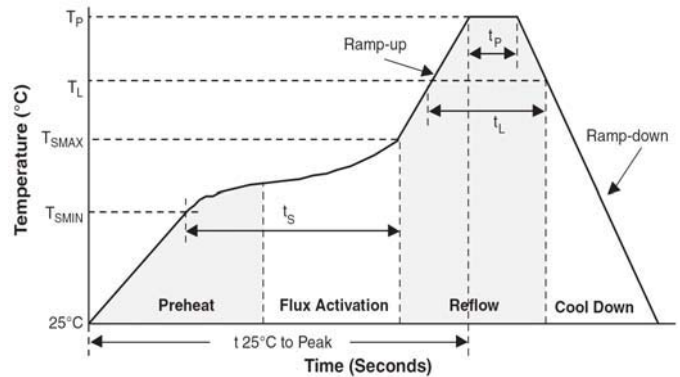
Dark grey areas show added PCB copper area for better thermal resistance.

Thermal Resistance vs Additional PCB Cu Area



Reflow Profile

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate (T _{max} to T _p)	3 °C/sec. max.
Preheat	
- Temperature Min. (T _{sm})	150 °C
- Temperature Max. (T _{smax})	200 °C
- Time (t _{sm} to t _{smax})	60-180 sec.
Time maintained above:	
- Temperature (T _L)	217 °C
- Time (t _L)	60-150 sec.
Peak/Classification Temperature (T _p)	260 °C
Time within 5 °C of Actual Peak Temp. (t _p)	20-40 sec.
Ramp-Down Rate	6 °C/sec. max.
Time 25 °C to Peak Temperature	8 min. max.

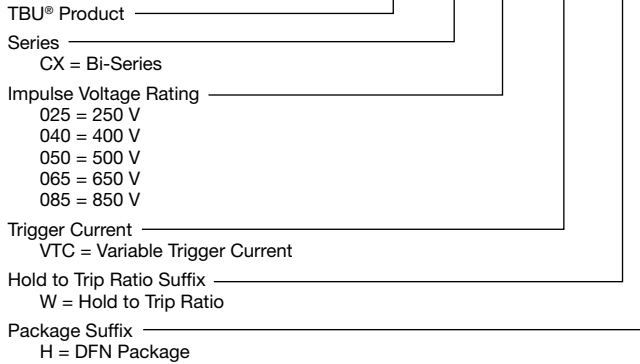


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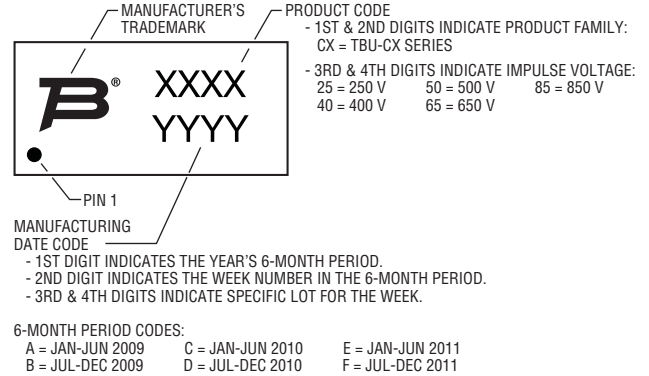
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How to Order

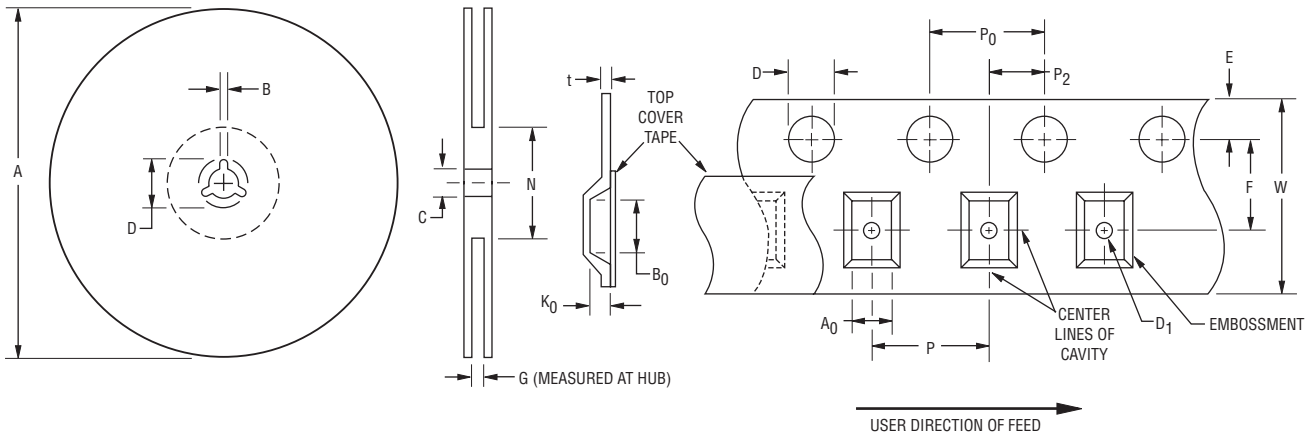
TBU - CX 085 - VTC - WH



Typical Part Marking



Packaging Specifications



QUANTITY: 3000 PIECES PER REEL

A		B		C		D		G	N
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Ref.	Ref.
326	330	1.5	2.5	12.8	13.5	20.2	-	16.5	102
(12.835)	(13.002)	(.059)	(.098)	(.504)	(.531)	(.795)		(.650)	(4.016)

A ₀		B ₀		D		D ₁		E		F	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
4.3	4.5	8.45	8.65	1.5	1.6	1.5	-	1.65	1.85	7.4	7.6
(.169)	(.177)	(.333)	(.341)	(.059)	(.063)	(.059)		(.065)	(.073)	(.291)	(.299)
K ₀		P		P ₀		P ₂		t		W	
Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
1.0	1.2	7.9	8.1	3.9	4.1	1.9	2.1	0.25	0.35	15.7	16.3
(.039)	(.047)	(.311)	(.319)	(.159)	(.161)	(.075)	(.083)	(.010)	(.014)	(.618)	(.642)

DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

REV. 12/10

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